

Multilayer Ceramic Chip Capacitors

C3225C0G3A103J250AC



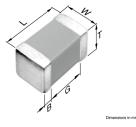






TDK item description C3225C0G3A103JT****

Applications	Commercial Grade Please refer to Part No. <u>CGA6P1C0G3A103J250AC</u> for Automotive use.	
Feature	High Voltage (1000V and over)	
Series	C3225 [EIA 1210]	
Status	Production	



Size		
Length(L)	3.20mm ±0.40mm	
Width(W)	2.50mm ±0.30mm	
Thickness(T)	2.50mm ±0.30mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)		
Recommended Land Pattern (PA)	2.00mm to 2.40mm	
Recommended Land Pattern (PB)	1.00mm to 1.20mm	
Recommended Land Pattern (PC)	1.90mm to 2.50mm	
Recommended Slit Pattern (SD)		

Electrical Characteristics		
Capacitance	10nF ±5%	
Rated Voltage	1kVDC	
Temperature Characteristic	COG(0±30ppm/°C)	
Q (Min.)	1000	
Insulation Resistance (Min.)	10000ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	1000pcs

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

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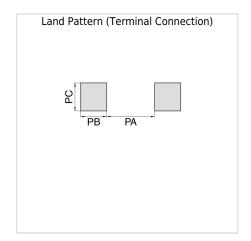








Associated Images



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